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HIGH-VOLTAGE LITHIUM-DRIFTED SILICON DETECTORS

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High-voltage Lithium-Drifted Silicon Detectors

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Abstract

A "double-drifted" geometry, which may take several forms, is described. The geometry makes possible the very-high-voltage operation of lithium-drifted silicon radiation detectors.
Introduction

Collection-time limitations of detectors having the etched mesa structure of Fig. 1 make it impractical to use finished devices much over 3 mm thick. The collection time of a 3-mm detector, at 25°C and normal voltages, is about 0.5 μsec. This collection time approaches the upper limit of practical use and increases in proportion to the square of the detector thickness. The current-vs-voltage curve of Fig. 2 is typical of that obtained with devices having this geometry. It will be seen that the leakage current rises rapidly above about 400 volts. Accompanying this increase in leakage is a large increase in noise from the detector. This places limits on the usable operating voltage. The increase in current at the higher voltages is due to the n-type channel which exists over the exposed intrinsic surface. As the detector voltage is increased, the channel reaches through to the i-p junction, and surface breakdown at the i-p junction results. Thus the effects of an n-type surface inversion layer must be overcome to permit high operating voltages if very thick lithium-drifted silicon detectors are to have sufficiently short collection times.

Double-Drift Geometry

The "double-drifted" structure of Fig. 3 automatically limits the channel length and thus prevents it from reaching through to the i-p junction. The function of the thin, peripheral intrinsic region, called a "shelf," is to provide a high, transverse field region which will cause depletion of the channel. Thus the effect of the n-type channel, of increasing the potential along the surface, is used to make the channel length self-limiting. Figure 4 shows surface voltage probe measurements which illustrate the self-limiting operation of the double-drift geometry. Figure 5 shows the room-temperature voltage-vs-current curve for a typical 3-mm-thick double-drifted detector. The onset of surface channel length limiting is apparent at 100 to 200 volts. Figure 6 shows the room-temperature voltage-vs-current curve for a 5-mm-thick double-drifted device.

Fabrication

The fabrication of very thick devices having the structure of Fig. 3 requires single-crystal silicon of large diameter. There are several ways in which small-diameter silicon may be used. The geometry illustrated in Fig. 7, with a rectangular mesa, has been fabricated successfully in the 5-to 7-mm thickness range. The geometry illustrated in Fig. 8, called a "top hat," seems very promising in the thickness range beyond 5 mm. A number of 5-mm-thick devices with this geometry have been fabricated, and larger devices are in process.

The geometry of Fig. 3 is fabricated as follows: Lithium is diffused into the entire surface of a silicon wafer of the desired thickness (Fig. 9a). The diffused wafer is masked and the sides etched to yield a diode with good reverse characteristics (Fig. 9b). The etched diode is drifted to obtain an intrinsic depth of about 0.5 mm (Fig. 9c). The drifted wafer is masked and etched to obtain a mesa of the required diameter (Fig. 9d). This device is
now drifted completely through (Fig. 9e). A thin gold entrance window\(^3\) and
varnish protection over a suitably treated surface complete the device (Fig. 9f).

**Application**

Devices 3-mm and 5-mm thick have been tested at 77°K, in low-
energy spectroscopy applications. Resolution of the order of 0.75 to 1.5 keV FWHM has been obtained with bias voltages in excess of 1000 volts. An immediate advantage of these devices in this, as well as other, applications is the minimizing of trapping effects.

The use of double-drifted 5-mm-thick devices in high-energy cyclotron experiments has been reported elsewhere.\(^4\)

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**References**


Fig. 1. Simple etched mesa geometry.
Fig. 2. V-I curve of a simple etched mesa device.
Fig. 3. Double-drift geometry - I.
Fig. 4. Surface voltage probe curves for a double-drifted device.
Fig. 5. V-I curve of a typical 3-mm-thick double-drifted device.
Fig. 6. V-I curve of a typical 5-mm-thick double-drifted device.
Fig. 7. Double-drift geometry - II.
Fig. 8. Double-drift geometry - III, "the top hat."
Fig. 9. Steps in double-drifted geometry production.
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